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AMENDMENTS TO THE CLAIMS:

This listing of claims will replace all prior versions, and listings, of claims in the application:

LISTING OF CLAIMS:

Claim 1 (canceled).

Claim 2 (currently amended): The chip electronic component according to claim 1, A chip electronic component comprising:

a body of the chip electronic component having outer peripheral surfaces including an upper surface, a lower surface and a pair of side surfaces;
an electronic component element having electrodes and defining part of said body of the chip electronic component; and

a plurality of external electrodes arranged to extend over at least the lower surface and at least one of the side surfaces of said body of the chip electronic component and electrically connected to the electrodes of the electronic component element; wherein

each portion of said external electrodes provided on the lower surface of said body of the chip electronic component is provided with a narrow portion and a wide portion; and

wherein the relationship L1<L2<L3 is satisfied, where L1 is the width of the external electrode portion located on said at least one of the side surfaces of said electric component element, L2 is the width of said narrow portion, and L3 is the width of said wide portion.

Claim 3 (currently amended): The chip electronic component according to claim 42, wherein said wide portion is substantially rectangular.

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Claim 4 (currently amended): The chip electronic component according to claim 42, wherein said wide portion is substantially circular.

Claim 5 (currently amended): The chip electronic component according to claim 42, wherein the wide portion is substantially triangular.

Claim 6 (currently amended): The chip electronic component according to claim 42, wherein a second wide portion is provided on the lower portion of the electronic component element.

Claim 7 (currently amended): The chip electronic component according to claim 42, wherein said electronic component element includes a piezoelectric resonant element.

Claim 8 (original): The chip electronic component according to claim 7, further comprising a first case substrate bonded to at least one side surface of said piezoelectric resonant element so as not to hinder the vibration of the piezoelectric resonant element.

Claim 9 (previously presented): The chip electronic component according to claim 8, further comprising a second case substrate disposed on the upper surface of said piezoelectric resonant element so as not to hinder the vibration of the piezoelectric resonant element.

Claim 10 (original): The chip electronic component according to claim 7, wherein said electronic component element further comprises a first case member and a second case member surrounding said piezoelectric resonant element.

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Claim 11 (original): The chip electronic component according to claim 8, wherein a recess is provided in the first case substrate.

Claim 12 (original): The chip electronic component according to claim 9, wherein a recess is provided in the second case substrate.

Claim 13 (currently amended): A mounting structure of a chip electronic component according to claim 42, wherein a bonding portion defined by a conductive bond does not extend outside of an outer periphery of the chip electronic component as seen from the top of the chip electronic component.

Claim 14 (previously presented): A chip electronic component comprising:
a body of the chip electronic component having outer peripheral surfaces including an upper surface, a lower surface and a pair of side surfaces;
an electronic component element having electrodes and defining part of said body of the chip electronic component; and
a plurality of external electrodes arranged so as to extend over at least the lower surface and at least one of the side surfaces of said body of the chip electronic component and electrically connected to the electrodes of the electronic component element;

wherein each portion of said external electrodes provided on the lower surface of said body of the chip electronic component is arranged to have an almost uniform width from one longitudinal end to the other, and satisfy the relation $L_1 < L_3$, where L_3 is the width of each portion of the external electrodes provided on the lower surface of said body of the chip electronic component, and L_1 is the width of each portion of the external electrodes provided on the at least one side surface of said body of the chip electronic component, each of the widths L_1 and L_3 being defined as a dimension of the

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external electrodes measured in a longitudinal direction of the body of the chip electronic component.

Claim 15 (original): The chip electronic component according to claim 14, wherein said electronic component element includes a piezoelectric resonant element.

Claim 16 (original): The chip electronic component according to claim 15, further comprising a first case substrate bonded to at least one side surface of said piezoelectric resonant element so as not to hinder the vibration of the piezoelectric resonant element.

Claim 17 (original): The chip electronic component according to claim 16, further comprising the second case substrate laminated on the upper surface of said piezoelectric resonant element so as not to hinder the vibration of the piezoelectric resonant element.

Claim 18 (original): The chip electronic component according to claim 15, wherein said electronic component element further comprises a first case member and a second case member surrounding said piezoelectric resonant element.

Claim 19 (original): A mounting structure of a chip electronic component comprising a chip electronic component mounted on said printed circuit board via a conductive bond according to claim 14, wherein the bonded portion defined by the conductive bond is located inside of the outer periphery of the chip electronic component as seen from the top of the chip electronic component.

Claim 20 (original): The chip electronic component according to claim 16, wherein a recess is provided in the first case substrate.

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Claim 21 (original): The chip electronic component according to claim 17,
wherein a recess is provided in the second case substrate.